

WHAT IS CLAIMED IS:

1. A memory card comprising:
a leadframe having a plurality of contacts;
at least one semiconductor die electrically connected to the leadframe; and
a body at least partially encapsulating the leadframe and including:
opposed top and bottom surfaces;
an opposed pair of longitudinal sides; and
an opposed pair of lateral sides;
the contacts of the leadframe being exposed in the bottom surface of the body and extending to one of the lateral sides thereof.
2. The memory card of Claim 1 wherein:
the bottom surface of the body is generally planar; and
each of the contacts defines a generally planar bottom surface which is substantially flush with the bottom surface of the body.
3. The memory card of Claim 1 wherein the body further includes a sloped side which extends between one of the lateral sides and one of the longitudinal sides thereof, the contacts extending to the lateral side which extends to the sloped side.
4. The memory card of Claim 1 wherein the leadframe includes seven contacts.
5. The memory card of Claim 1 wherein the leadframe further includes a pair of dummy pads which are exposed in the bottom surface of the body and extend to the lateral side thereof to which the contacts extend.
6. The memory card of Claim 5 wherein the leadframe includes seven contacts.
7. The memory card of Claim 6 wherein:
the body further includes a sloped side which extends between one of the longitudinal sides and one of the lateral sides thereof;
the contacts extend to the lateral side of the body which extends to the sloped side; and
one of the dummy pads extends to the sloped side, with the remaining one of the dummy pads extending to the lateral side to which the contacts extend.
8. The memory card of Claim 7 wherein:

the bottom surface of the body is generally planar; and
each of the contacts and each of the dummy pads defines a generally planar bottom surface which is substantially flush with the bottom surface of the body.

9. A memory card comprising:
a leadframe having a plurality of contacts;
at least one semiconductor die electrically connected to the leadframe; and
a body at least partially encapsulating the leadframe and including:
opposed top and bottom surfaces;
an opposed pair of longitudinal sides; and
an opposed pair of lateral sides;
the contacts of the leadframe being exposed in the bottom surface of the body and extending to a notch formed in the body and extending along one of the lateral sides thereof.

10. The memory card of Claim 9 wherein:
the bottom surface of the body is generally planar; and
each of the contacts defines a generally planar bottom surface which is substantially flush with the bottom surface of the body.

11. The memory card of Claim 9 wherein the body further includes a sloped side which extends between one of the lateral sides and one of the longitudinal sides thereof, the notch extending along the lateral side which extends to the sloped side and along at least a portion of the sloped side.

12. The memory card of Claim 9 wherein the leadframe includes seven contacts.

13. The memory card of Claim 9 wherein the leadframe further includes a pair of dummy pads which are exposed in the bottom surface of the body and extend to the notch.

14. The memory card of Claim 13 wherein the leadframe includes seven contacts.

15. The leadframe of Claim 14 wherein:

the body further includes a sloped side which extends between one of the longitudinal sides and one of the lateral sides thereof, the notch extending along at least a portion of the sloped side and along the lateral side which extends to the sloped side; and

one of the dummy pads extends to a portion of the notch extending along the sloped side, with the remaining one of the dummy pads extending to a portion of the notch which extends along one of the lateral sides.

16. The memory card of Claim 9 wherein the notch is partially defined by a shoulder which is perpendicularly recessed relative to the bottom surface of the body.

17. A method of fabricating a memory card, comprising the steps of:

- a) providing a leadframe having a plurality of contacts;
- b) electrically connecting at least one semiconductor die to the leadframe;
- c) partially encapsulating the leadframe and the semiconductor die with a body which includes opposed top and bottom surfaces, an opposed pair of longitudinal sides, and an opposed pair of lateral sides; and
- d) ablating a portion of the body in a manner facilitating the formation of a notch which extends between the contacts and one of the lateral sides of the body.

18. The method of Claim 17 wherein step (d) is accomplished through the use of a laser.

19. The method of Claim 17 wherein:

- step (c) comprises forming the body to include a sloped side which extends between one of the lateral sides and one of the longitudinal sides thereof; and
- step (d) comprises ablating the body such that the notch extends along at least a portion of the sloped side and along the lateral side which extends to the sloped side.

20. The method of Claim 19 wherein:

- step (a) comprises providing a leadframe which further includes a pair of dummy pads;
- step (c) comprises forming the body such that the dummy pads are exposed in the bottom surface thereof; and
- step (d) comprises ablating the body such that each of the dummy pads and each of the contacts extends to the notch formed in the body.